

Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	28
Terminal Finish	100 Sn
MS Number	MS010652B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.03 E-01	87.7	877000	63.30	632976
Thermosets	Epoxy Resin	Proprietary	2.87 E-02	5.0	50000	3.61	36088
Thermosets	Phenol Resin	Proprietary	2.87 E-02	5.0	50000	3.61	36088
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.15 E-02	2.0	20000	1.44	14435
Other inorganic materials	Carbon Black	1333-86-3	1.72 E-03	0.3	3000	0.22	2165
Subtotal			5.74 E-01	100	1000000	72.18	721752

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.97 E-01	97.5	975000	24.73	247338
Copper & its alloys	Iron	7439-89-6	4.74 E-03	2.35	23500	0.60	5961
Copper & its alloys	Zinc	7440-66-6	2.42 E-04	0.12	1200	0.03	304
Copper & its alloys	Phosphorus	7723-14-0	6.05 E-05	0.03	300	0.01	76
Subtotal			2.02 E-01	100.00	1000000	25.37	253680

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.22 E-03	100.0	1000000	0.15	1536

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.40 E-03	100.0	1000000	0.68	6789

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.27 E-03	99.99	1000000	0.16	1602

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.00 E-03	100.0	1000000	1.13	11319

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.11 E-03	80	800000	0.27	2658
Thermosets	Epoxy Resin	Proprietary	3.96 E-04	15	150000	0.05	498
Others	Curing agent & hardener	Proprietary	1.32 E-04	5	50000	0.02	166
Subtotal			2.64 E-03	100	1000000	0.33	3322

Package Totals			Weight (g) 7.95 E-01			Percentage (%) 100.00	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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